



**Silicon Motion, Inc.**

## **SM3267 Test Program and ISP Release Note**

**SM3267 Test Program and ISP Release Note:**

Release Date	ISP Version	ISP Check Sum	Test AP Version	Description
2013/09/02	130815-AB	SM3267ABISP.BIN	V 2.5.26 v7 13/08/26 Build	<ol style="list-style-type: none"><li>1. SM3267AB MP tool / FW first formal release</li><li>2. Support Samsung 1xnm 64Gb / 128Gb TLC: K9ACGD8U0B / K9ADGD8U0M</li><li>3. Support Micron 20nm 64Gb MLC L84: MT29F64G08CBABB</li></ol>
2013/10/07	131004-AB	SM3267ABISP.BIN	V 2.5.27 v8 13/10/4 Build	<ol style="list-style-type: none"><li>1. Update PHY setting</li><li>2. Performance improvement</li><li>3. Support Micron L85: MT29F128G08CBCAB</li><li>4. Support Intel L74 / L84: 29F64G08AAME1 / 29F16B08CAME1 / 29F32B08JAME1 / 29F16B08CCMF3 / 29F32B08JCMF3</li><li>5. Support Hynix 16nm UCG-D die: H27UCG8T2DTR</li><li>6. Support Toshiba 19nm 64Gb / 128Gb TLC: TC58TEG6T2JTA00 / TC58TEG7T2JTA00</li></ol>
2013/11/03	131023-AB	SM3267ABISP.BIN	V 2.5.28 v2 13/10/9 Build	<ol style="list-style-type: none"><li>1. Fix SPOR (手動超穩定) issue</li><li>2. Write performance improvement (L85)</li><li>3. Support Toshiba 19nm MLC 64GB, type B, type C: TC58TEG6DDJTA00, TC58TEG6DCJTA00, TH58TEG7CDJBA4C</li><li>4. Support Micron L84D: MT29F64G08CBCEB</li></ol>
2013/11/26	131119-AB	SM3267ABISP.BIN	V 2.5.29 v3 13/11/26 Build	<ol style="list-style-type: none"><li>1. Modify PHY (Sel_C) setting flow in MP process</li><li>2. Support Samsung 1xnm TLC ADG with 2CE/4Die:</li></ol>



				<p>K9CHGD8U1M</p> <ol style="list-style-type: none"><li>Support SanDisk 1ynm 64Gb MLC / TLC: SDTNRGAMA-008G, SDTNRCAMA-008G</li><li>Support Toshiba A19nm 64Gb MLC / TLC: TC58TEG6DDKTA00, TC58TEG6TCKTA00</li><li>Support Micron 16nm 128Gb MLC / L95B: 29F128G08CBECB</li><li>Adjust Intel &amp; Micron 16K/512page flash (L8X/L9X) default setting capacity.</li></ol>
2014/01/03	131216-AB	SM3267ABISP.BIN	V 2.5.31 v3 14/01/02 Build	<ol style="list-style-type: none"><li>Modify PHY Setting flow.</li><li>Enhance POR error handling in L85 4way interleave.</li><li>Support Samsung 19nm GBG-C die, K9GBGD8U0C</li><li>Support Micron 20nm 128Gb MLC L85C, MT29F128G08CBEBB</li><li>Support Micron 20nm 64Gb MLC L84C, MT29F64G08CBEDB</li></ol>